Product Change Notification

Change Notification #: **117890 - 00**

Change Title: **Minor Change**
Select Tray and Box Intel® Xeon® Processor E5 Series Processors,
PCN 117890-00, Product Material,
Visual Appearance Change to Lidded Products

Date of Publication: **November 25, 2020**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	February 25, 2021

Description of Change to the Customer:

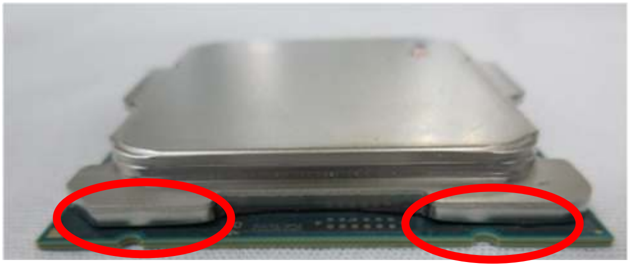
Due to tooling end-of-life constraints, discontinuing supplier support and process simplification, Intel will be changing their process for placing lids during the cure portion of the assembly process. This change will result in the following three visual changes to the package:

- There will be some additional sealant on the edge where the Lid meets the substrate
- There will be a break in the sealant placed on the substrate just under the lid
- The size of the Preform placed on the die will increase

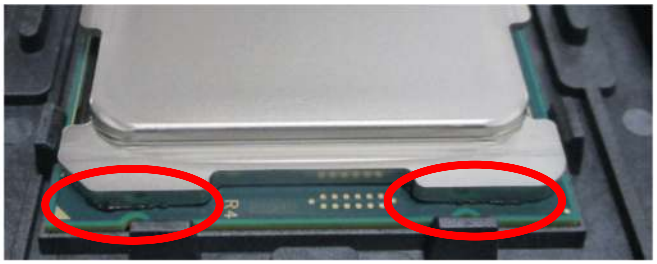
Note: The lid process referred to as "old placement process" in the pictures below uses an older technology placed by a specific tool that will end of life. The process referred to below as the "new placement process" although similar, is the next generation. Both the old placement process and the new placement process attach lids to units, accomplishing the same function. However, moving to the new placement process results in the three changes named within this notification.

1. Additional Sealant noticeable on edge where substrate and lid meet, causing a squished-out appearance.

Old Placement Process



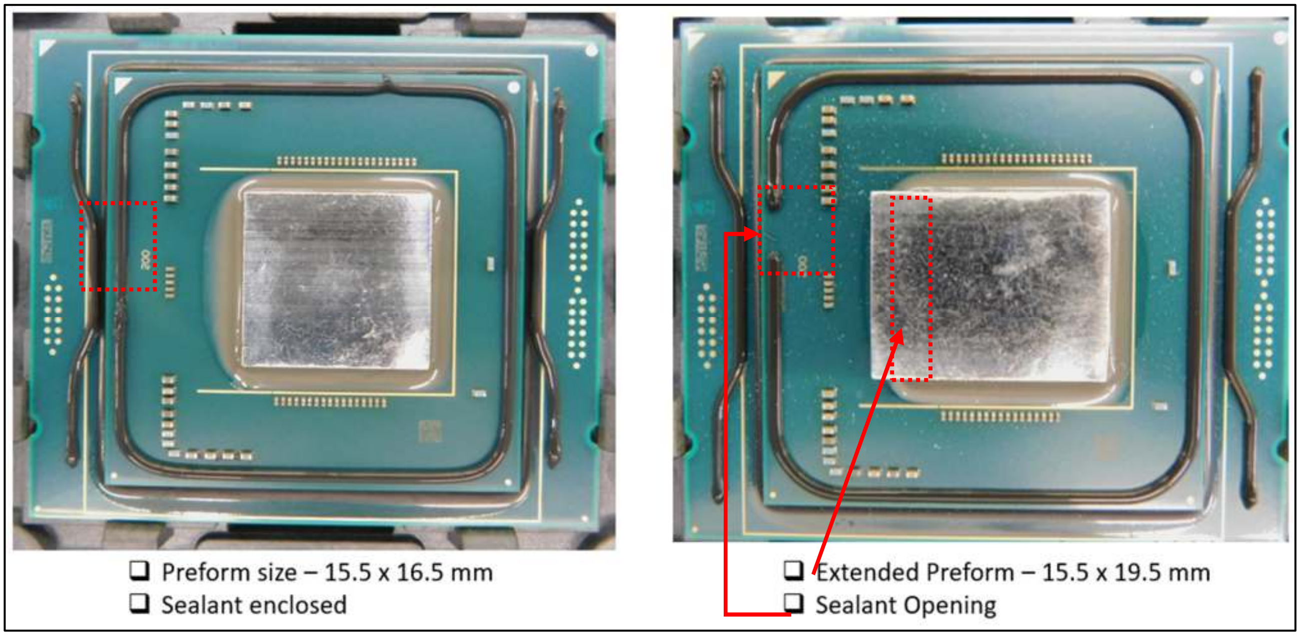
New Placement Process



(pictures are for reference only)

2. **A break in the sealant opening on the substrate on the underside of the lid**
   (see picture below, showing #2 and #3 change together)

3. **Preform size placed on the die will changes from 15.5 x 16.5 mm to 15.5 x 19.5 mm.**



Old Placement Process

New Placement Process

☐ Preform size – 15.5 x 16.5 mm
☐ Sealant enclosed

☐ Extended Preform – 15.5 x 19.5 mm
☐ Sealant Opening

(pictures for reference only. This picture shows both change #2 and #3 together, before and after)

These minor changes are visible to the customer upon inspection and will occur on Select Tray and Box Intel® Xeon® Processor E5 Series Processors listed in the Products Affected / Intel Ordering Codes table below.

Customer Impact of Change and Recommended Action:

This is a Minor change. There is no change to the Form, Fit or Function of the product as a result of this change. This is strictly a result of using different toolsets to accomplish the same task. Customers do not need to do anything as a result of this change.

Intel will not do a hard transition off of the old placement process to the new placement process. Therefore, customers should expect to see a limited mixture of finished goods until fully transitioned. However, the changes will start as early as February 25, 2021 as noted above.

Once Intel begins to transition, the older placement process will be discontinued and only the new process will be in place.

Please contact your Intel Representative with any questions or concerns regarding the change detailed in this notification.

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® Xeon® Processor E5-2640 v4	R0	CM8066002032701	S R2NZ	948123
Intel® Xeon® Processor E5-2603 v4	R0	CM8066002032805	S R2P0	948124
Intel® Xeon® Processor E5-2609 v4	R0	CM8066002032901	S R2P1	948125
Intel® Xeon® Processor E5-2630L v4	R0	CM8066002033202	S R2P2	948126
Intel® Xeon® Processor E5-2637 v4	R0	CM8066002041100	S R2P3	948127
Intel® Xeon® Processor E5-2643 v4	R0	CM8066002041500	S R2P4	948128
Intel® Xeon® Processor E5-2667 v4	R0	CM8066002041900	S R2P5	948129
Intel® Xeon® Processor E5-1620 v4	R0	CM8066002044103	S R2P6	948130

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® Xeon® Processor E5-1650 v4	R0	CM8066002044306	S R2P7	948131
Intel® Xeon® Processor E5-1680 v4	R0	CM8066002044401	S R2P8	948132
Intel® Xeon® Processor E5-2608L v4	R0	CM8066002045102	S R2P9	948136
Intel® Xeon® Processor E5-2618L v4	R0	CM8066002061300	S R2PE	948141
Intel® Xeon® Processor E5-1630 v4	R0	CM8066002395300	S R2PF	948142
Intel® Xeon® Processor E5-1603 v4	R0	CM8066002395400	S R2PG	948143
Intel® Xeon® Processor E5-2623 v4	R0	CM8066002402400	S R2PJ	948145
Intel® Xeon® Processor E5-1660 v4	R0	CM8066002646401	S R2PK	948146
Intel® Xeon® Processor E5-2620 v4	R0	CM8066002032201	S R2R6	948659
Intel® Xeon® Processor E5-2630 v4	R0	CM8066002032301	S R2R7	948660
Boxed Intel® Xeon® Processor E5-2640 v4	R0	BX80660E52640V4	S R2NZ	949004
Boxed Intel® Xeon® Processor E5-2603 v4	R0	BX80660E52603V4	S R2P0	949005
Boxed Intel® Xeon® Processor E5-2609 v4	R0	BX80660E52609V4	S R2P1	949006
Boxed Intel® Xeon® Processor E5-1620 v4	R0	BX80660E51620V4	S R2P6	949007
Boxed Intel® Xeon® Processor E5-2620 v4	R0	BX80660E52620V4	S R2R6	949499
Boxed Intel® Xeon® Processor E5-2630 v4	R0	BX80660E52630V4	S R2R7	949500
Boxed Intel® Xeon® Processor E5-1650 v4	R0	BX80660E51650V4	S R2P7	950795

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 25, 2020	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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